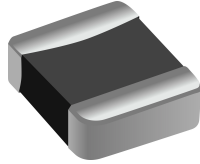


MATERIAL DECLARATION SHEET



Material Number	SRP2008DP series			
Product Line	Shielded SMD Power Inductor			
Compliance Date	2024/07/03			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [Mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Alloy Amorphous Powder	6.95	Iron (Fe)	7439-89-6	86.8%	46.404%	54.44
				Silicon (Si)	7440-21-3	6.7%	3.580%	
				Boron (B)	7440-42-8	2.5%	1.336%	
				Chromium (Cr)	7440-47-3	2.5%	1.336%	
				Carbon (C)	7440-44-0	0.7%	0.374%	
				Manganese (Mn)	7439-96-5	0.7%	0.374%	
				Phosphorus (P)	7723-14-0	0.04%	0.021%	
				Sulfur (S)	7704-34-9	0.015%	0.008%	
2	WIRE	COPPER(C11000)	4.28	Copper	7440-50-8	99.950%	32.891%	32.91
				Misc. ,not to declare	/	0.1%	0.017%	
		RESIN	0.23	Polyamide inide resin	25053-57-0	75.0%	1.326%	1.77
		Polyamide resin	70024-79-2	25.0%	0.442%			
3	Adhesive	Epoxy	0.3	Formaldehyde, polymer with (chloromethyl) oxirane and 2-methylphenol	29690-82-2	100.0%	2.310%	2.31
4	Hardening	resins	0.14	Phenol, polymer with formaldehyde	9003-35-4	100.0%	1.080%	1.08
5	Silver Paste	Silver	1.1	Silver (Ag)	7440-22-4	100.0%	8.460%	8.46
6	Plating	Plating- Ni	0.003	Nickel (Ni)	7440-02-0	100.0%	0.020%	0.02
		Plating- Sn	0.003	Tin (Sn)	7440-31-5	100.0%	0.020%	0.02
Total weight			13					

MATERIAL DECLARATION SHEET



This Document was updated on: 2024/07/03

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.